



RESPONSE UNDER 37 C.F.R.  
§1.116 EXPEDITED PROCEDURE  
EXAMINING GROUP 2823

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**Applicants:** Stephen L. Buchwalter, et al.

**Examiner:** Khiem D. Nguyen

**Serial No:** 09/782,494

**Art Unit:** 2823

**Filed:** February 13, 2001

**Docket:** YOR920000745US1 (14029)

**For:** BILAYER WAFER-LEVEL  
UNDERFILL

**Dated:** December 23, 2003

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

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**RESPONSE UNDER 37 C.F.R. §1.116**

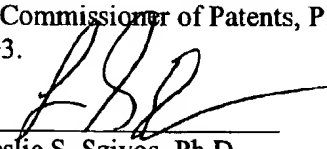
Sir:

In response to the Final Office Action dated September 24, 2003, applicants respectfully request that the following remarks be entered in the above-identified patent application.

**CERTIFICATE OF MAILING UNDER 37 C.F.R. §1.8(a)**

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner of Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on December 23, 2003.

Dated: December 23, 2003

  
Leslie S. Szivos, Ph.D.

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